

Title (en)

Electrolytic process for depositing a graded layer on a substrate and component

Title (de)

Elektrolytisches Verfahren zum Abscheiden einer gradierten Schicht auf ein Substrat und Bauteil

Title (fr)

Procédé électrolytique pour la déposition d'une couche graduelle sur un substrat et composant

Publication

EP 1526192 A1 20050427 (DE)

Application

EP 03024373 A 20031024

Priority

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Abstract (en)

The electroplating process, to deposit a coating on a substrate (13) or component, gives a graduated coating layer by altering the composition of the electrolyte (7) at timed intervals. The electrolyte within the bath (4), has at least two components (28,31), with an additional feed of the second component (31) in time intervals (t) to alter the electrolyte composition, or the first component (28) is taken out at least partially. The first component is a metal, especially an alloy, or a ceramic; and the second component is metallic. The electrolyte is agitated mechanically. The current/voltage pulses (40) are rectangular or triangular.

Abstract (de)

Bisherige elektrolytische Abscheidungsverfahren können gradierte Schichten nur schlecht aus den Bestandteilen auf ein Substrat abscheiden. Das erfindungsgemäße Verfahren ermöglicht das elektrolytische Abscheiden einer gradierten Schicht auf ein Substrat (13) durch zeitliche Variierung der Zusammensetzung des Elektrolyten (7). <IMAGE>

IPC 1-7

C25D 15/02; **C25D 5/18**; **C25D 5/12**; **C25D 5/20**; **F01D 5/28**

IPC 8 full level

C25D 5/00 (2006.01); **C25D 5/10** (2006.01); **C25D 5/18** (2006.01); **C25D 5/20** (2006.01); **C25D 15/02** (2006.01); **F01D 5/00** (2006.01); **F01D 5/28** (2006.01)

CPC (source: EP US)

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Citation (search report)

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